



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 197 FR4 35 L50.35 P18_10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly	
Layer-1	35 μ	Copper			
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)
	100 μ	Prepreg			
Layer-2	35 μ	Copper			
	500 μ	L-FR4			A1
Layer-3	35 μ	Copper			
	180 μ	Prepreg			(180 μ PrePreg-Type: 7628)
	180 μ	Prepreg			
Layer-4	35 μ	Copper			
	500 μ	L-FR4		A2	
Layer-5	35 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	35 μ	Copper			

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